

Supplementary Information for:

Blending induced stack-ordering and performance improvement in a solution-processed *n*-type organic field-effect transistor

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1. Optical, electrochemical and thermal properties of PTCDI-e.

The UV-vis absorption and FL emission spectra of PTCDI-e in CHCl₃ solution and thin film are shown in Figure S1. Compared with the peaks in the solution, the absorptions in thin film become broad with red-shift of 28, 36, 41 nm, respectively. The red shifts indicated the edge-to-face molecular aggregation (*i.e.* J-aggregation) in the solid state.

Figure S2 shows the cyclic voltammogram of PTCDI-e solution. Two reversible reduction waves were observed, but no oxidation wave could be observed. With the half-wave reduction potential $E_{1/2} = 1/2(-0.544-0.62) = -0.582$ V and using the ferrocene/ferrocenium (Fc/Fc⁺) as an internal standard, the LUMO level was determined by $E_{LUMO} = -[4.8 - E_{FOC} + E_{1/2}^{red}]$ eV $\approx -[4.4 + E_{1/2}^{red}]$ eV = -3.82 eV. From the solution absorption edge (Figure S1a), the HOMO-LUMO gap was calculated at 1.89 eV. According to the LUMO level and the HOMO-LUMO gap, the HOMO level was calculated at -5.71 eV.

The thermal properties of PTCDI-e are shown in Figure S3. Thermogravimetric analysis (TGA) displayed that PTCDI-e had good thermal stability with a high decomposition temperature. Two

endothermic peaks in the differential thermal analysis (DTA) indicated the appearance of liquid crystalline phase and the first one corresponding to the phase transition from solid to a highly ordered mesophase.

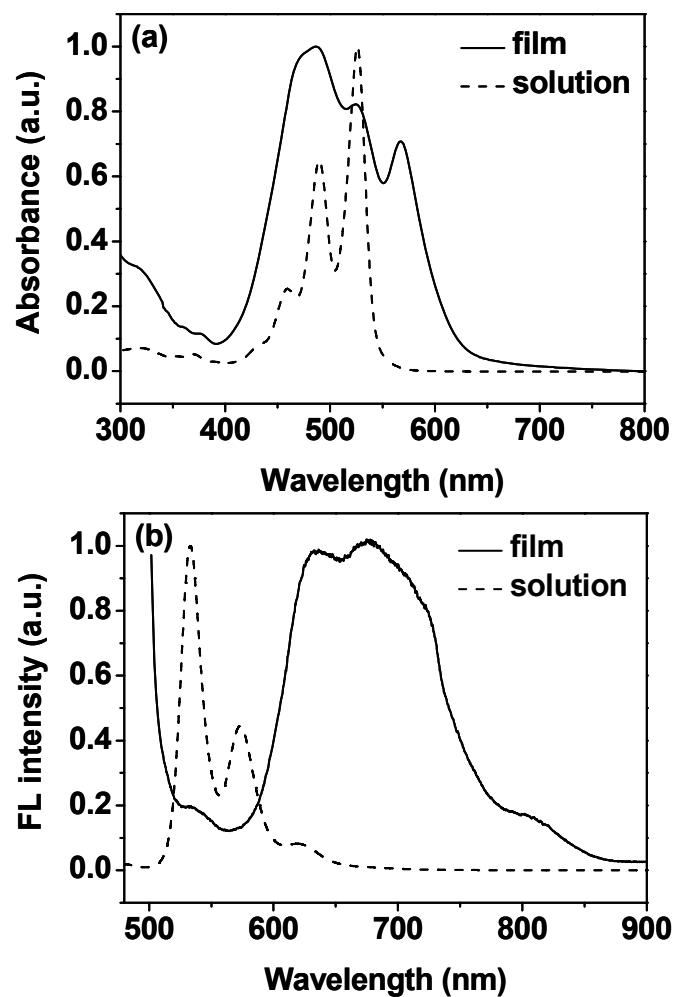


Figure S1. (a) UV-vis absorption and (b) FL emission spectra of PTCDI-e in CHCl_3 solution and thin film.

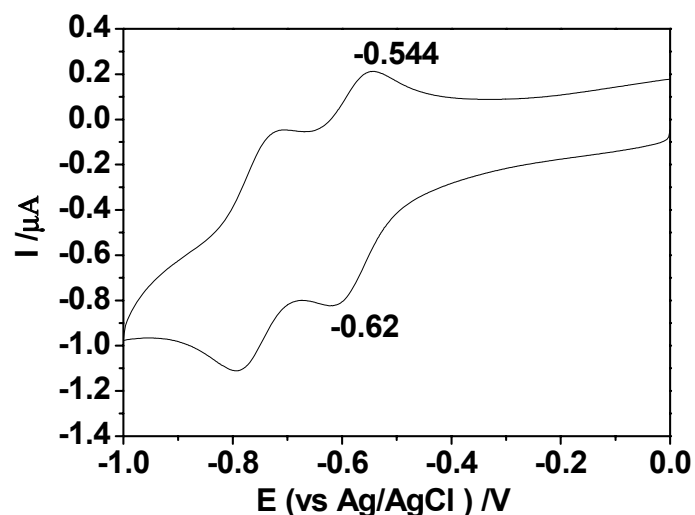


Figure S2. Cyclic voltammogram for PTCDI-e (0.1 mM compound and 0.1 M Bu_4NPF_4 in CH_2Cl_2 , Ag/AgCl as reference electrode and ferrocene as internal standard, scan rate 100 mV/s).

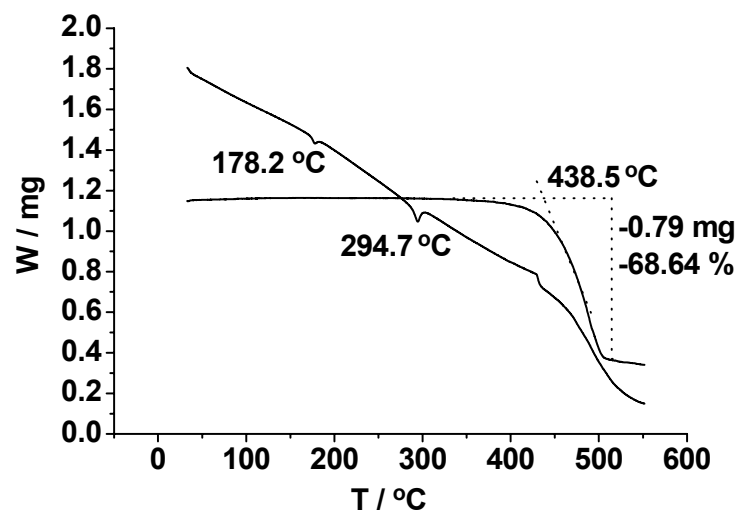


Figure S3. TGA and DTA plots of PTCDI-e with a heating rate of $10\text{ }^\circ\text{C}/\text{min}$ under N_2 .

2. Vacuum-Deposited OFETs.

PTCDI-e was vacuum deposited both on the bare and octadecyltrichlorosilane (OTS) treated Si/SiO₂ substrates with different substrate temperature (T_s) in the top-contact configuration to fabricate OFET devices. Thin films (50 nm thick) were vacuum deposited at $0.4\text{ \AA}/\text{s}$. The deposition rate and film

thickness were monitored by ULVAC CRTM-6000. All the devices were measured in vacuum. The performance data including electron field-effect mobility (μ), on/off current ratio ($I_{\text{on}}/I_{\text{off}}$), and threshold voltage (V_{T}) are summarized in Table S1. The best performance ($\mu = 0.279 \text{ cm}^2 \text{ V}^{-1} \text{ s}^{-1}$, $I_{\text{on}}/I_{\text{off}} = 1.1 \times 10^6$, $V_{\text{T}} = 2.6 \text{ V}$) was obtained from the devices fabricated on the bare Si/SiO₂ substrate at $T_{\text{S}} = 150 \text{ }^\circ\text{C}$. Figure S4 shows the transfer and output curves of a typical device.

The electron mobility was increased with the increasing of the substrate temperature both for the two different substrates. This can be explained by the crystallization and grain size. Figure S5 and Figure S6 show the X-ray diffraction (XRD) patterns and atomic force microscopy (AFM) images of the films. The increasing intensities resulted from the increase of the substrate temperature indicated the improvements of the crystallinity of films and ordering between molecular chains. High crystallinity and order caused strong intermolecular π - π stacking, which benefited the transport of charge carriers. Also, the size of the crystal grains stacking by molecular terraces increased with the increase of the substrate temperature. Larger grains resulted in fewer defects between the grain boundaries and higher mobility. Height of a terrace in the grains was calculate at $3.20 \pm 0.1 \text{ nm}$ by AFM, which is refer to the molecular length and corresponding to the (001) reflection at 3.20 nm ($2\theta = 2.76^\circ$) in Figure 4a.

Table S1. OFET performances of the vacuum-deposited devices.

substrate	T_{S} ($^\circ\text{C}$)	μ ($\text{cm}^2 \text{ V}^{-1} \text{ s}^{-1}$)	$I_{\text{on}}/I_{\text{off}}$	V_{T} (V)
Bare	28 (RT)	0.052	1.0×10^8	10.5
	60	0.115	1.4×10^8	12.6
	100	0.117	8.0×10^7	12.0
	150	0.279	1.1×10^6	2.6
Ots	28 (RT)	0.071	1.3×10^8	13.7
	60	0.107	7.0×10^7	17.6
	100	0.163	3.0×10^8	17.5
	150	0.165	1.1×10^6	4.7

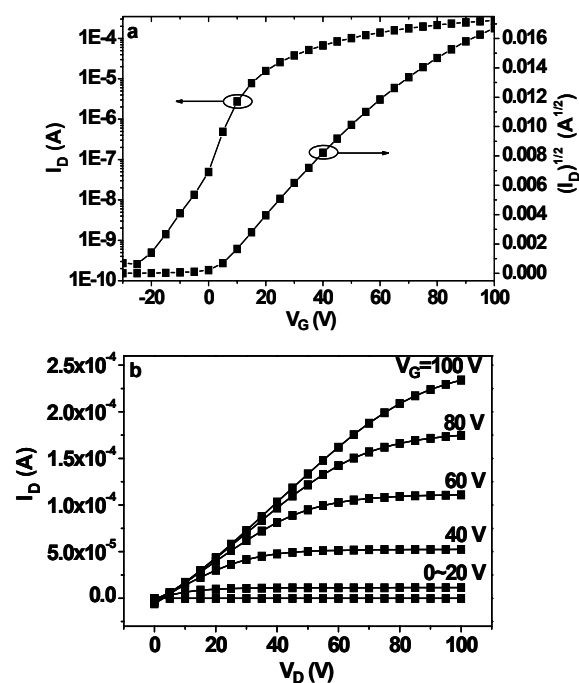


Figure S4. (a) Transfer ($V_D = 100$ V) and (b) output curves of the OFET fabricated on the bare Si/SiO₂ substrate at $T_S = 150$ °C.

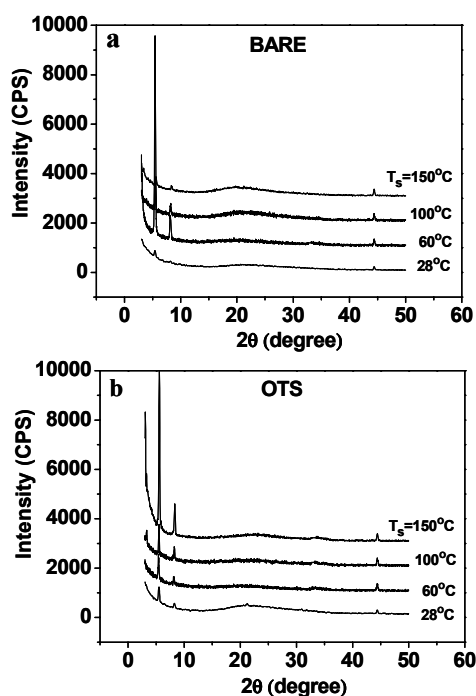


Figure S5. XRD patterns of the films deposited at different temperature: (a) bare Si/SiO₂ substrate and (b) OTS treated Si/SiO₂ substrate.

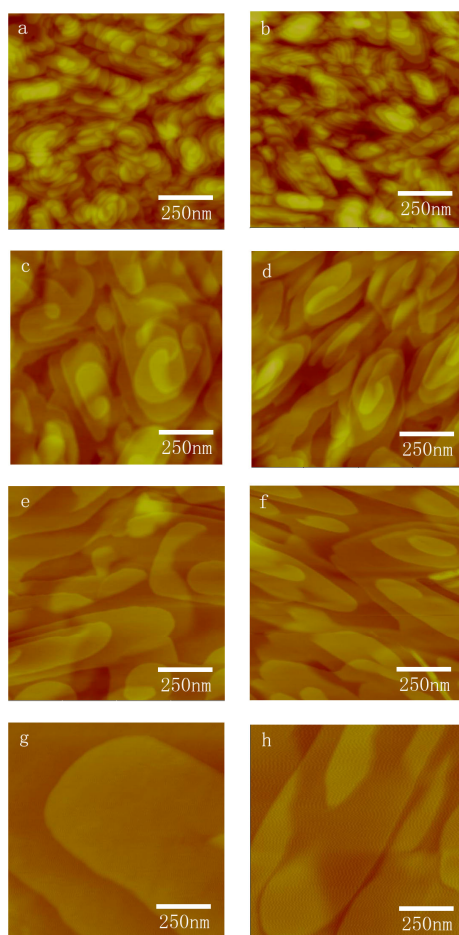


Figure S6. AFM images of the films deposited on: bare Si/SiO₂ substrate: (a) $T_S = 28\text{ }^\circ\text{C}$, (c) $T_S = 60\text{ }^\circ\text{C}$, (e) $T_S = 100\text{ }^\circ\text{C}$, (g) $T_S = 150\text{ }^\circ\text{C}$; OTS treated Si/SiO₂ substrate: (b) $T_S = 28\text{ }^\circ\text{C}$, (d) $T_S = 60\text{ }^\circ\text{C}$, (f) $T_S = 100\text{ }^\circ\text{C}$, (h) $T_S = 150\text{ }^\circ\text{C}$. (height scale 50 nm)

3. Solution-Processed films.

Table S2. Typical I_{off} and I_{on} of the PTCDI-e solution-processed OFETs.

blend materials	blending ratio (mol %)	I_{off} (A)	I_{on} (A)
TMTSF ^a	0	9.67×10^{-11}	4.11×10^{-6}
	9.05	5.43×10^{-11}	1.38×10^{-5}
	16.59	7.11×10^{-11}	1.87×10^{-5}
	28.46	1.46×10^{-9}	1.29×10^{-4}
	44.31	9.78×10^{-11}	2.59×10^{-5}
	54.41	3.76×10^{-11}	1.27×10^{-5}
TTF ^b	0	3.35×10^{-10}	1.89×10^{-6}
	17.86	4.51×10^{-10}	3.07×10^{-6}
	30.31	4.49×10^{-10}	3.67×10^{-6}
	46.52	5.41×10^{-10}	8.97×10^{-6}
	63.50	1.03×10^{-9}	1.38×10^{-5}
	72.30	2.78×10^{-10}	3.80×10^{-5}
	77.68	2.61×10^{-10}	5.15×10^{-5}
81.31	1.93×10^{-10}	1.65×10^{-5}	
TCNQ ^b	0	3.35×10^{-10}	1.89×10^{-6}
	17.86	2.28×10^{-10}	1.30×10^{-6}
	30.31	5.07×10^{-10}	5.96×10^{-7}
	46.52	2.11×10^{-10}	7.19×10^{-7}
	63.50	2.82×10^{-10}	6.44×10^{-7}

^aAnnealed at 150 °C after deposition. ^bAnnealed at 50 °C after deposition.

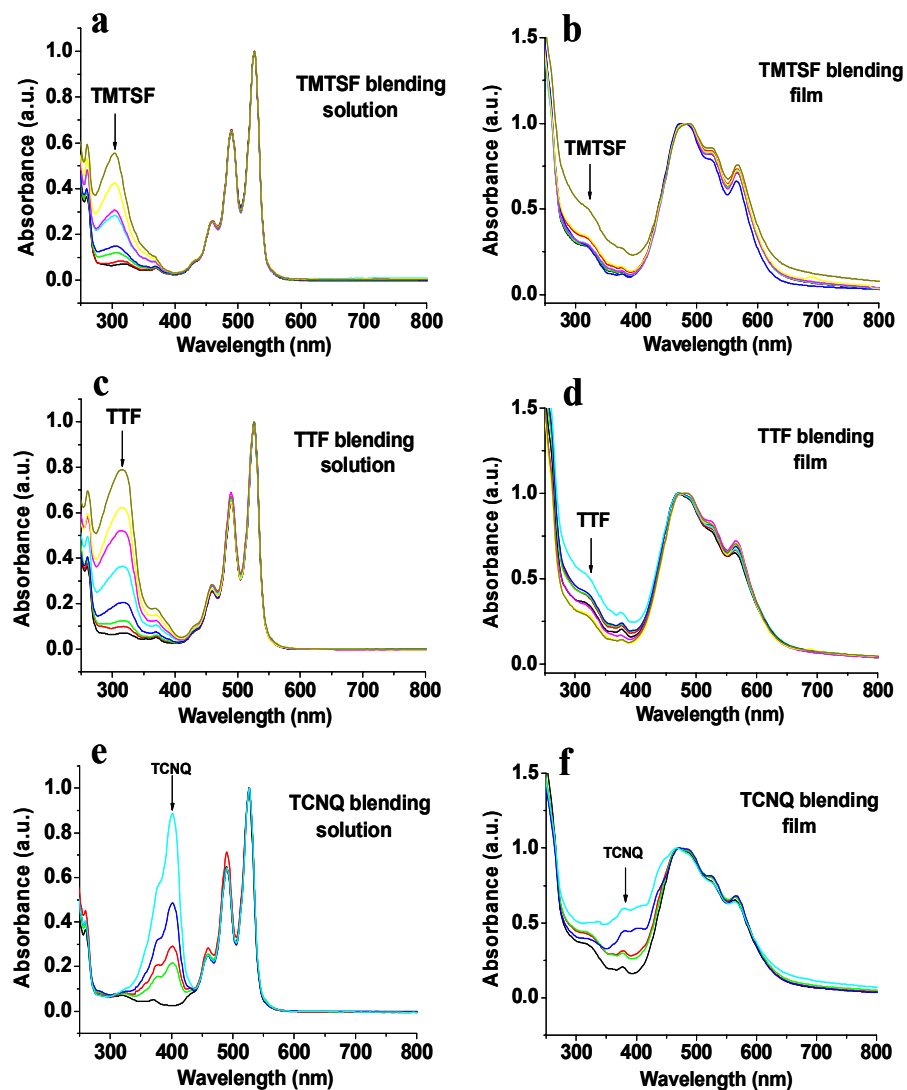


Figure S7. UV-vis absorption spectra of the blended PTCDI-e solutions and solid films.

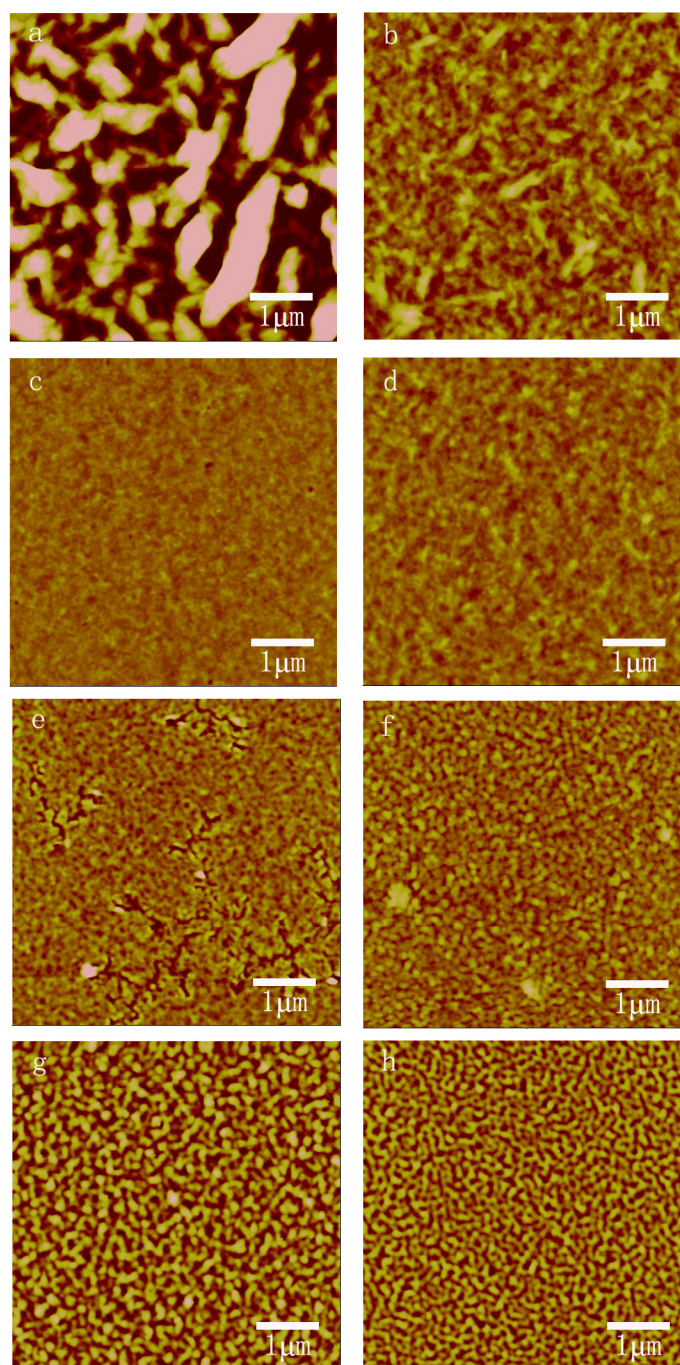


Figure S8. AFM images of the solution-processed PTCDI-e films blended with TTF at different ratios: (a) 0, (b) 17.86, (c) 30.31, (d) 46.52, (e) 63.50, (f) 72.30, (g) 77.68, (h) 81.31 mol %. (height scale 50 nm)

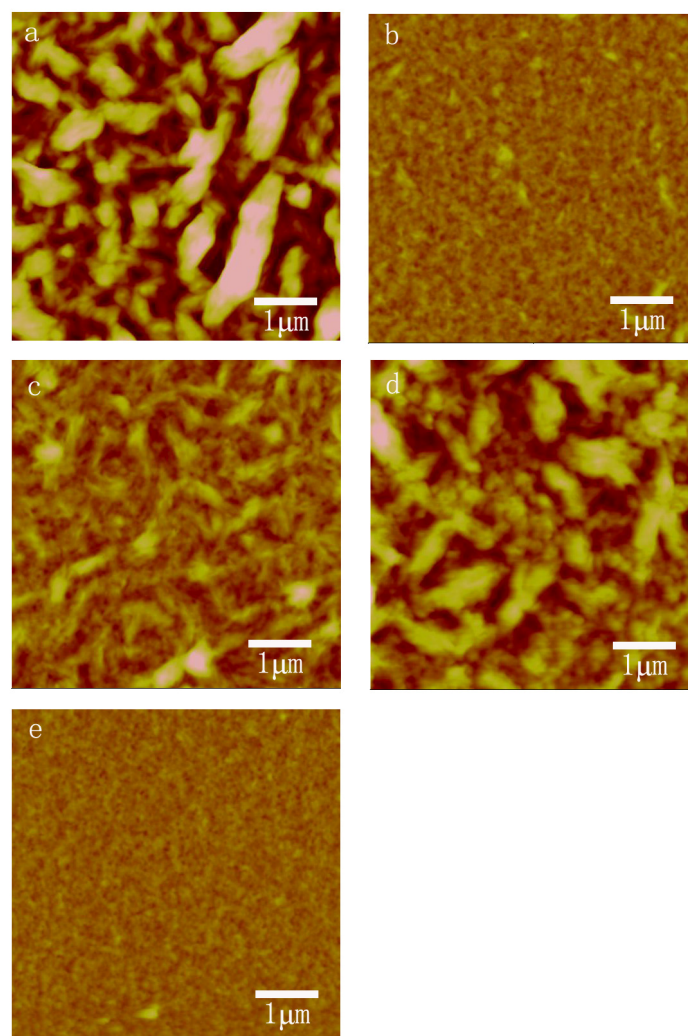


Figure S9. AFM images of the solution-processed PTCDI-e films blended with TCNQ at different ratios: (a) 0, (b) 17.86, (c) 30.31, (d) 46.52, (e) 63.50 mol %. (height scale 50 nm)